

**IN THE CLAIMS:**

**Please amend the claim as follows:**

1. (Currently Amended) An uncooled optical communication module comprising:  
a plate-shaped thermistor having a positive temperature coefficient so that resistance of the thermistor increases according to an increase of an environmental temperature;  
a semiconductor chip mounted on an upper surface of the thermistor; and,  
a driving means for applying a predetermined constant direct voltage to the thermistor and for controlling a temperature of the thermistor based on the environmental temperature.

2. (Original) The uncooled optical communication module as claimed in claim 1, wherein the thermistor has a heating characteristic defined by an equation,

$$P = \frac{V^2}{R}, \text{ wherein } P \text{ represents a power consumption amount corresponding to a heating}$$

value of the thermistor,  $V$  represents a voltage applied to the thermistor, and  $R$  represents a resistance of the thermistor.

3. (Original) The uncooled optical communication module as claimed in claim 1, wherein the driving mean includes:

a first electrode and a second electrode laminated on both sides of the thermistor; and  
a voltage source connected to the first electrode and the second electrode, which applies a predetermined voltage.

4. (Original) The uncooled optical communication module as claimed in claim 1, wherein the semiconductor chip is a semiconductor laser chip emitting light through one end of the semiconductor chip.

5. (Currently Amended) An optical communication module comprising:

a thermistor having a positive temperature coefficient so that resistance of the thermistor increases according to an increase of an environmental temperature;

a semiconductor chip thermally coupled to the thermistor; and,

a plurality of electrodes, coupled to the thermistor, arranged to connect the thermistor to a constant direct voltage source to the thermistor capable of controlling a temperature of the thermistor based on the environmental temperature.

6. (Original) The optical communication module as claimed in claim 5, wherein the thermistor has a heating characteristic defined by an equation,

$$P = \frac{V^2}{R}, \text{ wherein } P \text{ represents a power consumption amount corresponding to a heating}$$

value of the thermistor,  $V$  represents a voltage applied to the thermistor, and  $R$  represents a resistance of the thermistor.

7. (Original) The optical communication module as claimed in claim 5, wherein a voltage source is connected to the first electrode and the second electrode, which applies a predetermined voltage to the thermistor.

8. (Original) The optical communication module as claimed in claim 5, wherein the semiconductor chip is a semiconductor laser chip emitting light through one end of the semiconductor chip.

9. (Original) The optical communication module as claimed in claim 5, wherein the semiconductor chip is a semiconductor optical amplifier.